

# Specification of Thermoelectric Module

## TEC1-26318

### Description

The 263 couples, 50 mm × 50 mm size module which is made of selected high performance ingot to achieve superior cooling performance and greater delta T up to 70 °C, designed for superior cooling and heating up to 100 °C applications. If higher operation or processing temperature is required, please specify, we can design and manufacture the custom made module according to your special requirements.

### Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

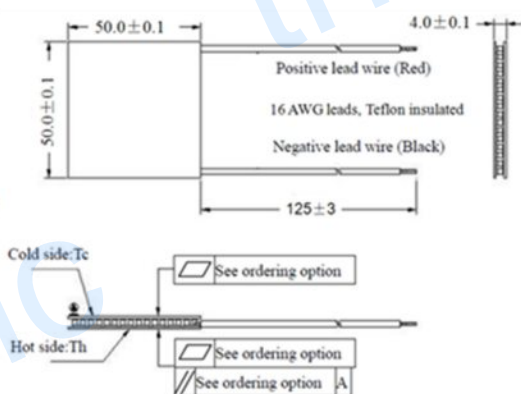
### Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

### Performance Specification Sheet

Th(°C)	27	50	Hot side temperature at environment: dry air, N <sub>2</sub>
DT <sub>max</sub> (°C)	70	79	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side
U <sub>max</sub> (Voltage)	32.6	35.2	Voltage applied to the module at DT <sub>max</sub>
I <sub>max</sub> (amps)	17.1	17.1	DC current through the modules at DT <sub>max</sub>
Q <sub>Cmax</sub> (Watts)	360.1	387.7	Cooling capacity at cold side of the module under DT=0 °C
AC resistance(ohms)	1.45	1.56	The module resistance is tested under AC
Tolerance (%)	± 10		For thermal and electricity parameters

### Geometric Characteristics Dimensions in millimeters



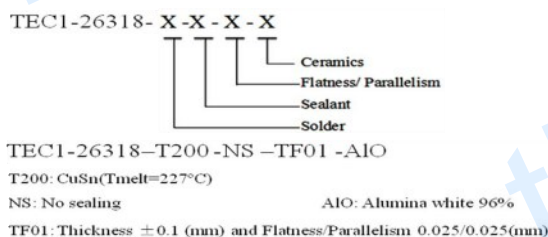
### Ordering Option

Suffix	Thickness (mm)	Flatness/Parallelism (mm)	Lead wire length(mm) Standard/Optional length
TF	0:4.0±0.1	0:0.05/0.05	125±3/Specify
TF	1:4.0±0.05	1:0.025/0.025	125±3/Specify
Eg. TF01: Thickness 4.0 ± 0.1 (mm) and Flatness 0.025 / 0.025 (mm)			

### Manufacturing Options

- |  |   |
|--|---|
| <b>A. Solder:</b>                          | <b>C. Ceramics:</b>                                     |
| 1. T100: BiSn (T <sub>melt</sub> =138°C)   | 1. Alumina (Al <sub>2</sub> O <sub>3</sub> , white 96%) |
| 2. T200: CuSn (T <sub>melt</sub> = 227 °C) | 2. Aluminum Nitride (AlN)                               |
| <b>B. Sealant:</b>                         | <b>D. Ceramics Surface Options:</b>                     |
| 1. NS: No sealing (Standard)               | 1. Blank ceramics (not metallized)                      |
| 2. SS: Silicone sealant                    | 2. Metallized (Au plating)                              |
| 3. EPS: Epoxy sealant                      |   |
| 4. Customer specify sealing                |   |

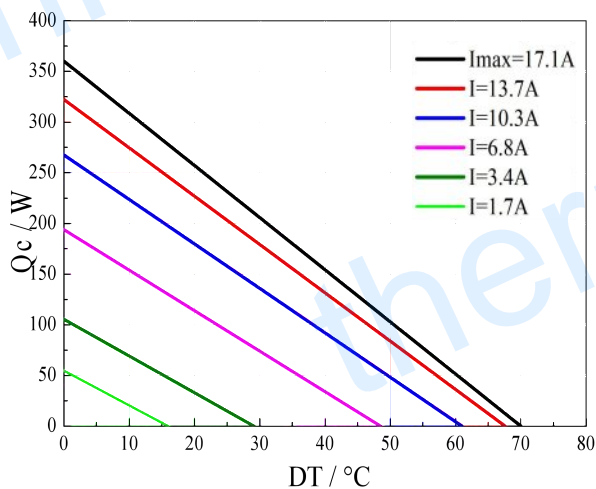
### Naming for the Module



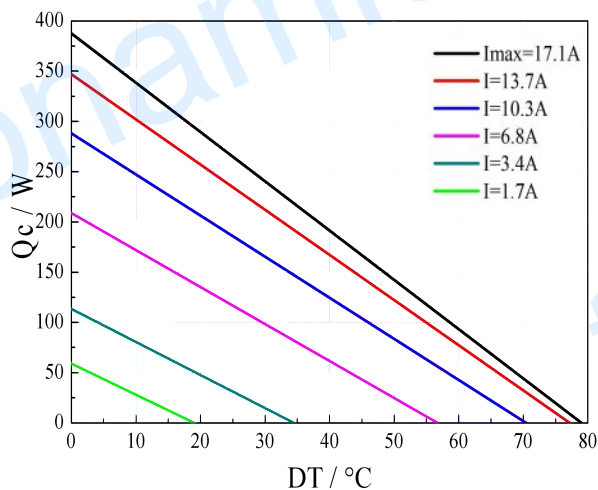
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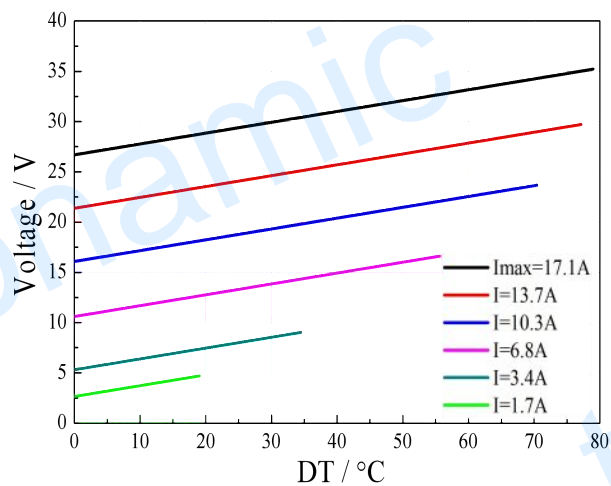
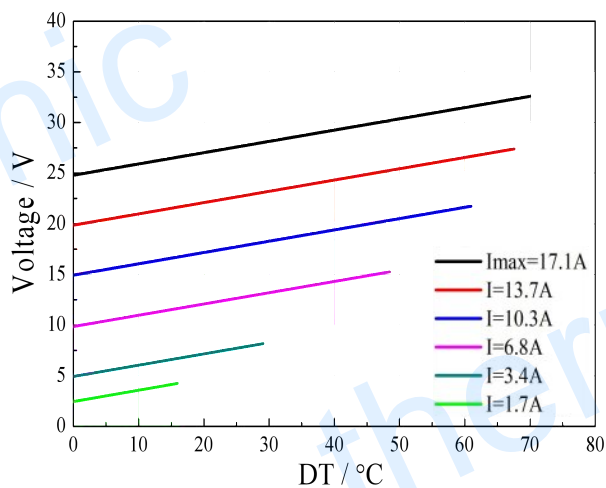
### Performance Curves at $T_h=27^\circ\text{C}$



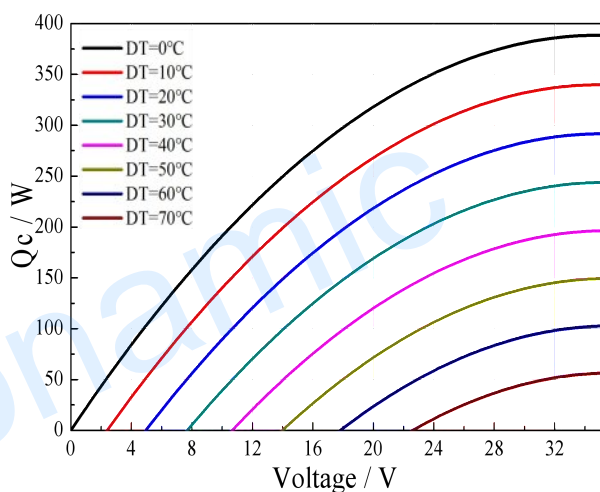
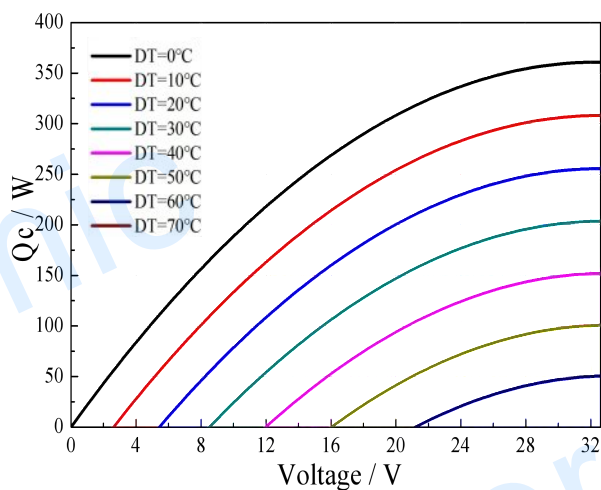
### Performance Curves at $T_h=50^\circ\text{C}$



Standard Performance Graph  $Q_c = f(DT)$



Standard Performance Graph  $V = f(\Delta T)$

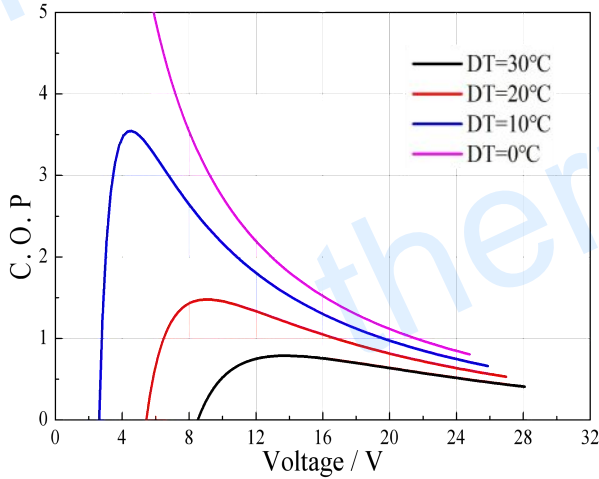


Standard Performance Graph  $Q_c = f(V)$

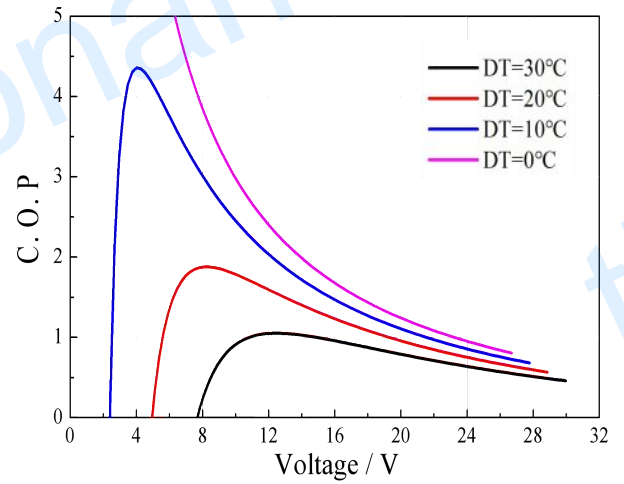
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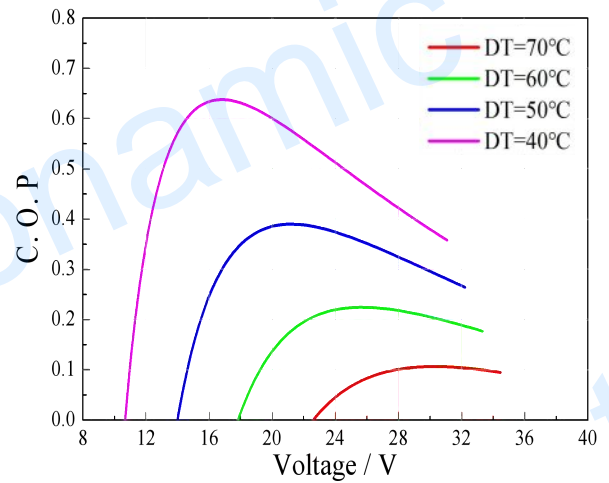
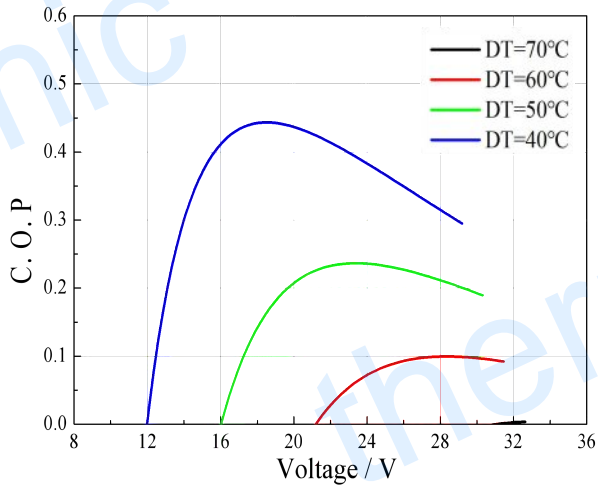
### Performance Curves at Th=27 °C



### Performance Curves at Th=50 °C



Standard Performance Graph COP = f(V) of  $\Delta T$  ranged from 0 to 30 °C



Standard Performance Graph COP = f(V) of  $\Delta T$  ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power  $Q_c$ /Input power ( $V \times I$ ).

### Operation Cautions

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating.
- Operation or storage module below 100 °C
- Operation below  $I_{max}$  or  $V_{max}$
- Work under DC